

What is claimed is:

1. A barrier rib of a plasma display panel, comprising:
 - a white paste layer formed on a glass substrate; and
 - 5 a photosensitive black resist layer formed on the white paste layer.
2. The barrier rib of claim 1, wherein the glass substrate comprises a lower glass substrate having an under layer, an address electrode, and a lower dielectric layer stacked thereon successively.
 - 10 3. The barrier rib of claim 1, wherein the white paste layer and the photosensitive black resist layer are formed to have uniform heights, respectively by printing.
 - 15 4. The barrier rib of claim 1, wherein the photosensitive black resist layer is formed of an inorganic material and comprises PbO or non-PbO glass powder, black pigment, and Al₂O₃ powder.
 5. The barrier rib of claim 4, wherein the PbO or non-PbO glass powder and Al₂O₃ powder have a particle diameter of 1~2μm.
 - 20 6. The barrier rib of claim 1, wherein the photosensitive black resist layer is formed of a paste phase having a viscosity of 30,000~40,000cps.
 - 25 7. The barrier rib of claim 1, wherein the photosensitive black resist

layer is formed of an organic material and comprises photopolymerizable monomer, photopolymerization initiator, binder polymer, and solvent.

8. The barrier rib of claim 1, wherein the photosensitive black resist
5 layer includes paraffin wax.

9. The barrier rib of claim 8, wherein the paraffin wax provides the photosensitive black resist layer with resistance against sandblasting.

10 10. A method of forming a barrier rib of PDP, comprising the steps of:
..... forming a white paste layer on a glass substrate and forming a photosensitive black resist layer on the white paste layer;
..... forming a photosensitive black resist pattern by patterning the photosensitive black resist layer;
15 heating the photosensitive black resist pattern so that a wax component contained in the photosensitive black resist pattern diffuses inside the photosensitive black resist pattern; and
..... removing a portion of the white paste layer failing to be covered with the photosensitive black resist pattern and plasticizing the photosensitive black resist
20 pattern and the remaining photosensitive black resist pattern.

11. The method of claim 10, wherein the glass substrate comprises a lower glass substrate having an under layer, an address electrode, and a lower dielectric layer stacked thereon successively.

12. The method of claim 10, wherein the white paste layer and the photosensitive black resist layer are formed to have uniform heights, respectively by printing.

5 13. The method of claim 10, wherein the photosensitive black resist layer is formed of an inorganic material and comprises PbO or non-PbO glass powder having a particle diameter of 1~2 μ m, black pigment, and Al₂O₃ powder having a particle diameter of 1~2 μ m.

10 14. The method of claim 10, wherein the photosensitive black resist layer is formed of a paste phase having a viscosity of 30,000~40,000cps.

15 15. The method of claim 10, wherein the photosensitive black resist layer is formed of an organic material and comprises photopolymerizable monomer, photopolymerization initiator, binder polymer, and solvent.

16. The method of claim 10, wherein the photosensitive black resist layer includes paraffin wax.

20 17. The method of claim 16, wherein the paraffin wax provides the photosensitive black resist layer with resistance against sandblasting.

25 18. The method of claim 10, wherein the portion of the white paste layer failing to be covered with the photosensitive black resist pattern is removed by sandblasting.

19. The method of claim 10, wherein the heating step is performed at 100~200°C for 30 minutes.